MECHANICAL DATA

MPBG204A - OCTOBER 2001 - REVISED FEBRUARY 2002

PLASTIC BALL GRID ARRAY

33,00 TYP 35,20 1,00 SQ 34,80 33,25 0,50 SQ 32,75 AP AM AN AL ALAAAAYVTPMKHFD ALAAAAYVTPMKHFD 1,0 0,50 L J G E C в Α 1 3 5 7 9 11 13 15 17 19 21 23 25 27 29 31 33 2 4 6 8 10 12 14 1618 20 22 24 26 28 30 32 34 A1 Corner **Bottom View** ∠ Heat Slug 4,00 MAX <u>1,50</u> 1,03 ¥ Seating Plane <u>0,70</u> 0,50 $\oplus \phi$ 0,10 M △ 0,20 0,60 ╼┝┝ 0,40 4203347-5/C 02/02

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Flip chip application only.

GPN (S-PBGA-N1156)



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